

CLAIMS

1. A packaging device of a hollow cathode sputtering target, comprising: a hollow cathode sputtering target; a cover of a size capable of covering a void of said target, one or more through-holes provided to said cover, a resin bag of a size capable of covering said through-holes, and a device for performing vacuum suction to the inside of said bag.
2. The packaging device of a hollow cathode sputtering target according to claim 1, wherein said cover is transparent resin.
3. The packaging device of a hollow cathode sputtering target according to claim 1 or claim 2, wherein said resin bag is a bag that is impermeable to oxygen and moisture.
4. The packaging device of a hollow cathode sputtering target according to any one of claims 1 to 3, wherein said cover has rigidity, and is formed from a flat plate that is capable of maintaining its shape after the vacuum suction.
5. A packaging method of a hollow cathode sputtering target, comprising the steps of installing a cover of a size capable of covering a void of said target; providing one or more through-holes to said cover; placing a resin bag over said through-holes, and performing vacuum suction to the inside of said bag.
6. The packaging method of a hollow cathode sputtering target according to claim 5, wherein said cover is transparent resin.
7. The packaging method of a hollow cathode sputtering target according to claim 5 or claim 6, wherein said resin bag is a bag that is impermeable to oxygen and moisture.
8. The packaging method of a hollow cathode sputtering target according to any one of claims 5 to 7, wherein said cover has rigidity, and is formed from a flat plate that is capable of maintaining its shape after the vacuum suction.